



Product Change Notification: CAAN-13TVEF852

Date:

19-Aug-2026

Product Category:

16-Bit Microcontrollers

Notification Subject:

CCB 8428 Final Notice: Qualification of MMT as an additional assembly site for selected PIC24FJ128GL303, PIC24FJ32GP203, PIC24FJ32GU203, PIC24FJ64GL303, PIC24FJ64GP203 and PIC24FJ64GU203 device families available in 36L UQFN (5x5x0.6mm) package.

Affected CPNs:

[CAAN-13TVEF852_Affected_CPN_08192026.pdf](#)

[CAAN-13TVEF852_Affected_CPN_08192026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MMT as an additional assembly site for selected PIC24FJ128GL303, PIC24FJ32GP203, PIC24FJ32GU203, PIC24FJ64GL303, PIC24FJ64GP203 and PIC24FJ64GU203 device families available in 36L UQFN (5x5x0.6mm) package.

Pre and Post Summary Changes:

	Pre Change	Post Change		Change (Yes/No)
Assembly Site	ASE Inc. (ASE)	ASE Inc. (ASE)	Microchip Technology Thailand (B ranch) (MMT)	Yes

Wire Material	CuPdAu	CuPdAu	CuPdAu	No
Die Attach Material	FH-900 (PFAS-free)	FH-900 (PFAS-free)	QMI519 (PFAS-free)	Yes
Molding Compound Material	CEL-9240HF	CEL-9240HF	G700LTD	Yes
Lead-Frame Material	C7025	C7025	EFTEC64T	Yes
Lead-Frame Lead Lock	No	No	Yes, locking hole	Yes
Lead-Frame Design	See Pre and Post Change Summary for Comparison			

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability and on-time delivery performance by qualifying MMT as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 30 October 2026 (date code: 2644)

Note Below EFSD: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	August 2026					>	October 2026				
Work Week	31	32	33	34	35		40	41	42	43	44
Qual Report Availability				X							
Final PCN Issue Date				X							
Estimated Implementation Date											X

Method to Identify Change: Traceability Code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Note: This is a qualification by similarity (QBS) to CCB 6825 and CCB 7830.

Revision History: August 19, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_CAAN-13TVEF852_Qual_Report_CCB6825.pdf](#)

[PCN_CAAN-13TVEF852_Qual_Report_CCB7830.pdf](#)

[PCN_CAAN-13TVEF852_Pre and Post_Change_Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN):

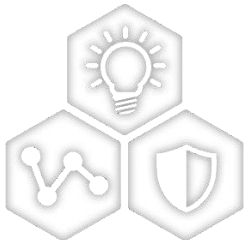
PIC24FJ128GL303-E/M5
PIC24FJ128GL303-I/M5
PIC24FJ128GL303T-I/M5
PIC24FJ32GP203-E/M5
PIC24FJ32GP203-I/M5
PIC24FJ32GP203T-I/M5
PIC24FJ32GU203-E/M5
PIC24FJ32GU203-I/M5
PIC24FJ32GU203T-I/M5
PIC24FJ64GL303-E/M5
PIC24FJ64GL303-I/M5
PIC24FJ64GL303T-I/M5
PIC24FJ64GP203-E/M5
PIC24FJ64GP203-I/M5
PIC24FJ64GP203T-I/M5
PIC24FJ64GU203-E/M5
PIC24FJ64GU203-I/M5
PIC24FJ64GU203T-I/M5

CCB 8428

Pre and Post Change Summary
PCN #: CAAN-13TVEF852

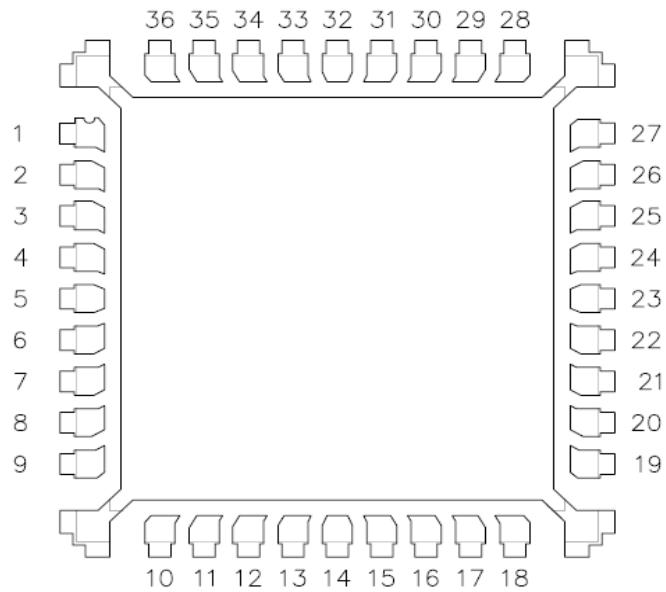
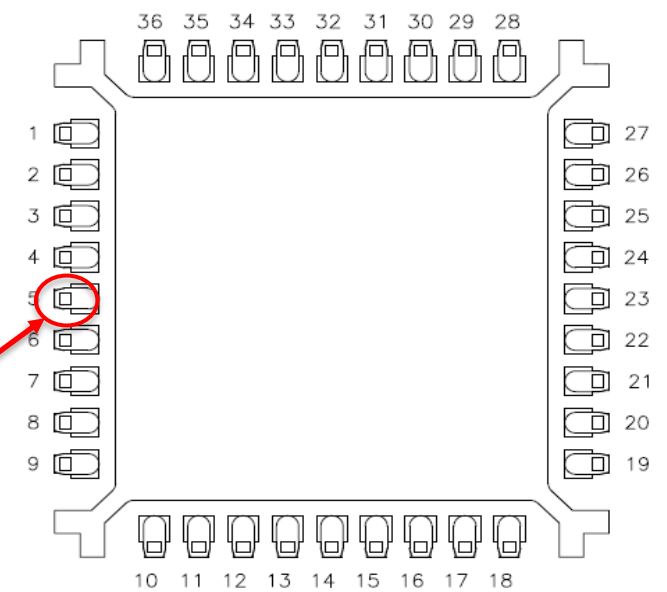


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Lead Frame Comparison

ASE	MMT								
 Diagram of the ASE lead frame showing 36 pins (1-18 on the bottom, 19-36 on the top) and a central square area. The pins are arranged in a standard lead frame configuration.	 Diagram of the MMT lead frame showing 36 pins (1-18 on the bottom, 19-36 on the top) and a central square area. A red circle highlights a locking hole on the left side of the frame, labeled "Lead-lock".								
<table><tr><td>Lead-frame Material</td><td>C7025</td></tr><tr><td>Lead-frame Lead Lock</td><td>None</td></tr></table>	Lead-frame Material	C7025	Lead-frame Lead Lock	None	<table><tr><td>Lead-frame Material</td><td>EFTEC64T</td></tr><tr><td>Lead-frame Lead Lock</td><td>Yes, *locking hole</td></tr></table>	Lead-frame Material	EFTEC64T	Lead-frame Lead Lock	Yes, *locking hole
Lead-frame Material	C7025								
Lead-frame Lead Lock	None								
Lead-frame Material	EFTEC64T								
Lead-frame Lead Lock	Yes, *locking hole								

Note1: Not to scale

*Note2: Mold compound materials fills the lead lock hole, which provides improved protection against moisture penetration along the edge of the leads (pins) of the package.



Qualification Report Summary

RELIABILITY LABORATORY

PCN #: CAAN-13TVEF852

Date:

September 26, 2024

Qualification of MMT as an additional assembly site for selected PIC24FJ128GL303, PIC24FJ32GP203, PIC24FJ32GU203, PIC24FJ64GL303, PIC24FJ64GP203 and PIC24FJ64GU203 device families available in 36L UQFN (5x5x0.6mm) package. This is a Q100 Grade 1 qualification.

PACKAGE QUALIFICATION REPORT

Purpose: Qualification of MMT as an additional assembly site for selected PIC24FJ128GL303, PIC24FJ32GP203, PIC24FJ32GU203, PIC24FJ64GL303, PIC24FJ64GP203 and PIC24FJ64GU203 device families available in 36L UQFN (5x5x0.6mm) package. This is a Q100 Grade 1 qualification.

CN: E000217173
QUAL ID: R2400531
QUAL ID Rev.: A
MP CODE: SAB054PTXFXF
Part No.: PIC24FJ512GU405-E/M4
Bonding No.: BD-002136 Rev. 01
CCB No.: 6825 and 8428

Lead Frame

Paddle Size: 193 x 193 mils
Material: EFTECT64T
DAP Surface Prep: Cu-RT
Process: ETCHED
Lead Lock: Yes
Part Number: 10104827
Lead Plating: MATTE Sn

Bond Wire

Wire: Au wire

Die Attach Material

Epoxy: QMI519

Mold Compound

Mold Compound: G700LTD

Package

Type: 48L UQFN-CA
Package Size: 6 x 6 x 0.6 mm

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MMT-244900782.000	SCB1923528839.220	2410CR2
MMT-244900783.000	SCB1923528839.220	2410EMV
MMT-244900784.000	SCB1923528839.220	2410G6C

Result: **Pass**

Conclusion:

48L UQFN-CA (6x6x0.6 mm) assembled by MMT pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Precondition Prior Perform Reliability Tests (At MSL Level 1)	Electrical Test: +25°C, 85°C and 125°C System: J750	JESD22-A113	693(0)	0/693	Pass	Good Devices
	Bake 150°C, 24 hrs. System: CHINEE	JIP/IPC/JEDEC J-STD-020E	693			
	85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH		693			
	3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243		693			
	Electrical Test: +25°C, 85°C and 125°C System: J750		693(0)	0/693	Pass	
Temp Cycle	Stress Condition: -55°C to +150°C, 1000 Cycles System: TABAI ESPEC TSA-70H	JESD22-A104	231(0)	0/231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C, 85°C and 125°C System: J750			0/231	Pass	77 units / lot
	Bond Strength: Wire Pull (>2.50 grams)		15(0)	0/15	Pass	
UNBIASED-HAST	Stress Condition: +130°C/85%RH, 96 hrs. System: HAST 6000X	JESD22-A118	231(0)	0/231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: J750			0/231	Pass	77 units / lot
HAST	Stress Condition: +130°C/85%RH, 96 hrs. Bias Volt: 3.6 Volts, 1.8 Volts, System: HAST 6000X	JESD22-A110	231(0)	0/231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C, 85°C and 125°C System: J750			0/231	Pass	77 units / lot

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
High Temperature Storage Life	Stress Condition: Bake 175°C, 500 hrs. System: TPS Bake Oven	JESD22-A103	45(0)	0/45		45 units
	Electrical Test: +25°C, 85°C and 125°C System: J750			0/45	Pass	
Solderability Temp 245°C	Steam Aging: Temp 93°C,8Hrs System: SAS-3000	J-STD-002	22(0)	0/22		
	Solder Dipping: Solder Temp.245°C Solder material: Pb Free Sn 95.5Ag3.9 Cu0.6 System: ERSA RA 2200D			0/22		
	Visual Inspection: External Visual Inspection			0/22	Pass	
Bond Strength Data Assembly	Wire Pull (>2.50 grams)	Mil. Std. 883-2011	30(0) Wires	0/30	Pass	
	Bond Shear (>15.00 grams)	CDF-AEC-Q1 00-001	30(0) bonds	0/30	Pass	



Qualification Report Summary

RELIABILITY LABORATORY

PCN #: CAAN-13TVEF852

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September 26, 2024

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MICROCHIP Package Qualification Report

Purpose: Qualification of MMT as an additional assembly site for selected PIC24FJ128GL303, PIC24FJ32GP203, PIC24FJ32GU203, PIC24FJ64GL303, PIC24FJ64GP203 and PIC24FJ64GU203 device families available in 36L UQFN (5x5x0.6mm) package. This is a Q006 Grade 1 qualification.

CCB No: 7830 and 8428

Misc.	Assembly site	MMT
	BD Number	BD-003648-01
	MP Code (MPC)	S01029U3XV01
	Part Number (CPN)	SST26VF064B-104V/MF70SV01
	Assembly Shipping Media (T/R, Tube/Tray)	Tube
	Base Quantity Multiple (BQM)	98
Lead-Frame	Paddle size	150x173
	Material	A194
	DAP Surface Prep	Bare Cu
	Treatment	Roughening LF
	Process	Etched LF
	Lead-lock	Dimple
	Part Number	10100878
	Lead Plating	Matte Tin
Bond Wire	Material	CuPdAu
Die Attach	Part Number	QMI519 (PFAS Free)
	Conductive	Yes
MC	Part Number	G700LTD
PKG	PKG Type	WSON
	Pin/Ball Count	8L
	PKG width/size	6x5x0.8mm



MICROCHIP

Package Qualification Report

Manufacturing Information

Assembly Lot No.
MMT-270400943.000
MMT-270401555.000
MMT-270401558.000

Result: Pass

Conclusion:

Qualification of S0102 mask / SST26VF064B-104V/MF70SV01 product CuPdAu wire in 8L WSON 6x5x0.8mm package at MMT site is qualified for MSL1 at 260°C as per JEDEC J-STD-020 standard and is passed in accordance to Specified JEDEC and Mil Standards



MICROCHIP Package Qualification Report

Moisture Soak Precondition Prior to Stresses

Test Method	JESD22-A113, JEDEC J-STD-020		
Test Condition	MSL1: 150°C 24 hours Bake, 168 hours Moisture Soak at 85°C/85%RH, 3x Reflow at 260°C		
Required Sample Size	231 units each lot / 3 lots;		
Lot ID	R2600518-1 MMT-270400943.000	R2600518-2 MMT-270401555.000	R2600518-3 MMT-270401558.000
Electrical Results (Fail / Pass)	0/231	0/231	0/231
Electrical Test Tester: NEXTEST_GV2X	25°C, 105°C and 125°C		
Result	Passed		

High Temp Storage

Test Method	JESD22-A103		
Test Condition	175°C / 500 hours		
Required Sample Size	45 units each lot / 3 lots;		
Lot ID	R2600518-1 MMT-270400943.000	R2600518-2 MMT-270401555.000	R2600518-3 MMT-270401558.000
Electrical Results (Fail / Pass)	0/45	0/45	0/45
WBP (Fail / Pass)	0/3	0/3	0/3
WBS (Fail / Pass)	0/3	0/3	0/3
Electrical Test Tester: NEXTEST_GV2X	25°C, 105°C and 125°C		
Result	Passed		



MICROCHIP

Package Qualification Report

Temperature Cycling

Test Method	JESD22-A104		
Test Condition	-55°C / +150°C Air to Air / 1000 Cycles		
Required Sample Size	77 units each lot / 3 lots;		
Lot ID	R2600518-1 MMT-270400943.000	R2600518-2 MMT-270401555.000	R2600518-3 MMT-270401558.000
Electrical Results (Fail / Pass)	0/77	0/77	0/77
WBP (Fail / Pass)	0/3	0/3	0/3
WBS (Fail / Pass)	0/3	0/3	0/3
Electrical Test Tester: NEXTEST_GV2X	25°C, 105°C and 125°C		
Result	Passed		

Biased HAST

Test Method	JESD22-A110		
Test Condition	+130°C / 85%RH / 96 hours / Bias Voltage: 3.6V		
Required Sample Size	77 units each lot / 3 lots;		
Lot ID	R2600518-1 MMT-270400943.000	R2600518-2 MMT-270401555.000	R2600518-3 MMT-270401558.000
Electrical Results (Fail / Pass)	0/77	0/77	0/77
WBP (Fail / Pass)	0/3	0/3	0/3
WBS (Fail / Pass)	0/3	0/3	0/3
Electrical Test Tester: NEXTEST_GV2X	25°C, 105°C and 125°C		
Result	Passed		



MICROCHIP Package Qualification Report

Unbiased HAST

Test Method	JESD22-A118		
Test Condition	+130°C / 85%RH / 96 hours		
Required Sample Size	77 units each lot / 3 lots;		
Lot ID	R2600518-1 MMT-270400943.000	R2600518-2 MMT-270401555.000	R2600518-3 MMT-270401558.000
Electrical Results (Fail / Pass)	0/77	0/77	0/77
Electrical Test Tester: NEXTEST_GV2X	25°C		
Result	Passed		

Solderability (0 Hr) Method 1: Dip and Look

Test Method	J-STD-002 / JESD22B-102
Test Condition / Criteria	Pb-free 8 hours Steam age. Dip at 245°C, 100% leads >95% lead coverage
Required Sample Size	22 units / 1 lot
Visual Result (Fail / Pass)	0/22
Result	Passed



MICROCHIP

Package Qualification Report

Wire Pull

Test Method	Mil. Std. 883-2011
Test Criteria	Bond Strength Data Assembly
Required Sample Size	5 units / 1 lot
Result (Fail / Pass)	0/5
Result	Passed

Bond Shear

Test Method	CDF-AEC-Q100-001
Test Criteria	Bond Strength Data Assembly
Required Sample Size	5 units / 1 lot
Result (Fail / Pass)	0/5
Result	Passed